

Amendments to the Specification:

At page 3, please add the following new paragraph after paragraph [0021]:

[0021a] FIG. 7 is an exploded view of the various elements to be stacked in the order in which they connect to one side of the printed circuit card using a chock.

Page 7, please amend paragraphs [0048] and [0049] as follows:

[0048] As a precaution, the integrated circuits 4A and 4B are mounted one after the other. The mounting of the first integrated circuit 4A is done by means of a chock 40, as shown in FIG. 5, that replaces the second assembly, which has not yet been mounted. This chock 40 is representative of the thickness of an assembly.

[0049] After the first integrated circuit 4A has been mounted, the chock 40 is removed. The standoffs being capable of moving in a direction perpendicular to the printed circuit card, the mounting of the second integrated circuit 4B to the other side of the printed circuit card is done by means of a tool 35. FIG. 5 is a view of an exemplary embodiment of such a tool.

Page 7, please amend paragraph [0051] as follows,:

[0051] During the mounting, or removal followed by a remounting, of this second integrated circuit 4B, the tool 35, i.e., a package tool 35, is placed, for example, on a horizontal support 50, as shown in FIG. 5, the shafts 29-30 being directed upward. The printed circuit card 2 is placed on this package tool 35 in order to insert the assembly A created into the package tool 35, the axes of the standoffs 16-19 coinciding with the axes of the shafts 29-30 of the package tool 35. As shown in

FIG. 5, when the printed circuit card 2 is placed on the package tool 35, the chock 40 is accessible for removal prior to the installation of the second integrated circuit 4B.

Page 8, please amend paragraph [0061] as follows:

[0061] A preliminary step consists of inserting, through the holes 11-14 provided for this purpose in the printed circuit 2, and on the opposite side of the printed circuit card onto which the integrated circuit 4A is to be mounted, a center chock 70, as shown in FIG. 7. This center chock 70 is equivalent in size to a plate 24A or 24B, but with a thickness representative of the thickness of an assembly. The springs are placed around the standoffs and the center chock 70 is pressed against the printed circuit card 2 by means of screws 20B-23B.

At page 10, please amend paragraphs [0081] and [0083] as follows:

[0081] Next, as shown in FIG. 7, the assembly A is placed inside the package tool 35 so that the springs 31-32 of the ~~containing~~ package tool 35 come into contact with the heads of the screws of the assembly A, which results in the configuration shown in FIG. 5.

[0083] The next step consists of removing the center chock 70 inserted in step E1. During the removal of the center chock 70, the springs 31-32 of the package tool 35 exert a force that compensates for the weight of the assembly A inside the package tool 35 and thus prevents the standoffs and the assembly A from moving in a direction perpendicular to the plane of the printed circuit card 2.